

#### **Features**

- Low On-Resistance
  - 13mΩ @ V<sub>GS</sub> = -10V
  - 16mΩ @ V<sub>GS</sub> = -4.5V
- 22mΩ @ V<sub>GS</sub> = -2.5V
- Low Gate Threshold Voltage
- Low Input Capacitance
- Fast Switching Speed
- Low Input/Output Leakage
- Lead Free By Design/RoHS Compliant (Note 2)
- "Green" Device (Note 4)
- Qualified to AEC-Q101 Standards for High Reliability

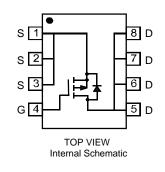
#### **Mechanical Data**

- Case: SO-8
- Case Material: Molded Plastic, "Green" Molding Compound. UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminals Connections: See Diagram
- Terminals: Finish Matte Tin annealed over Copper lead frame.
  Solderable per MIL-STD-202, Method 208
- Marking Information: See Page 4
- Ordering Information: See Page 4
- Weight: 0.072g (approximate)

SO-8



TOP VIEW



#### **Maximum Ratings** $@T_A = 25^{\circ}C$ unless otherwise specified

Chara	cteristic		Symbol	Value	Units
Drain-Source Voltage			V <sub>DSS</sub>	-20	V
Gate-Source Voltage			V <sub>GSS</sub>	±12	V
Drain Current (Note 1)	Steady State	T <sub>A</sub> = 25°C T <sub>A</sub> = 70°C	ID	-10 -8	A
Pulsed Drain Current (Note 3)			I <sub>DM</sub>	-35	А

# **Thermal Characteristics**

Characteristic	Symbol	Value	Unit
Total Power Dissipation (Note 1)	PD	2.5	W
Thermal Resistance, Junction to Ambient	R <sub>0JA</sub>	50	°C/W
Operating and Storage Temperature Range	T <sub>J,</sub> T <sub>STG</sub>	-55 to +150	°C

Notes: 1. Device mounted on 2 oz. Copper pads on FR-4 PCB.

2. No purposefully added lead.

3. Pulse width  ${\leq}10\mu S,$  Duty Cycle  ${\leq}1\%.$ 

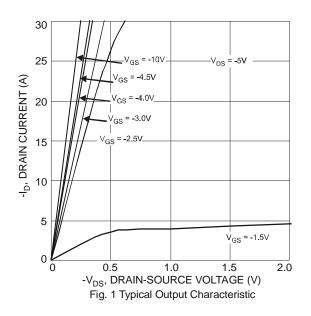
4. Diodes Inc.'s "Green" policy can be found on our website at http://www.diodes.com/products/lead\_free/index.php.

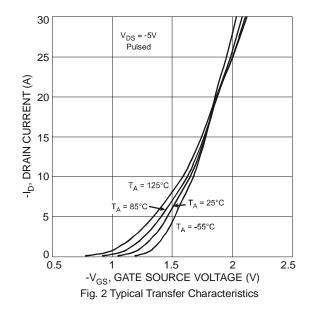


# Electrical Characteristics @T<sub>A</sub> = 25°C unless otherwise specified

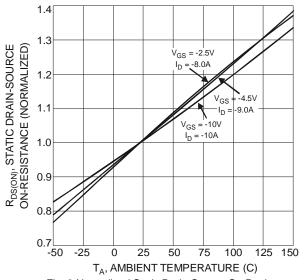
Characteristic	Symbol	Min	Turn	Max	Unit	Test Condition
	Symbol	Min	Тур	Max	Unit	Test Condition
OFF CHARACTERISTICS (Note 5)	51		1			
Drain-Source Breakdown Voltage	BV <sub>DSS</sub>	-20		—	V	$V_{GS} = 0V, I_D = -250\mu A$
Zero Gate Voltage Drain Current	I <sub>DSS</sub>		—	-1	μΑ	$V_{DS} = -20V, V_{GS} = 0V$
Gate-Source Leakage	I <sub>GSS</sub>		_	±100	nA	$V_{GS} = \pm 12V, V_{DS} = 0V$
ON CHARACTERISTICS (Note 5)						
Gate Threshold Voltage	V <sub>GS(th)</sub>	-0.6	0.77	-1.1	V	$V_{DS} = V_{GS}, I_D = -250 \mu A$
		_	8	13		$V_{GS} = -10V, I_D = -10A$
Static Drain-Source On-Resistance	R <sub>DS (ON)</sub>	_	11	16	mΩ	$V_{GS} = -4.5V, I_D = -9A$
		_	17	22		$V_{GS} = -2.5V, I_D = -8A$
Forward Transconductance	<b>g</b> fs	_	28	_	S	$V_{DS} = -10V, I_D = -10A$
Diode Forward Voltage (Note 5)	V <sub>SD</sub>	-0.5	0.68	-1.2	V	$V_{GS} = 0V, I_{S} = -3A$
DYNAMIC CHARACTERISTICS (Note 6)	-			-		·
Input Capacitance	Ciss	_	2444		pF	
Output Capacitance	Coss	_	594	_	pF	<sup>−</sup> V <sub>DS</sub> = -10V, V <sub>GS</sub> = 0V −f = 1.0MHz
Reverse Transfer Capacitance	C <sub>rss</sub>	_	556	_	pF	
Gate Resistance	R <sub>G</sub>	_	2.0	_	Ω	$V_{GS} = 0V V_{DS} = 0V, f = 1MHz$
SWITCHING CHARACTERISTICS (Note 6)						
Total Gate Charge	0	_	28.1 —		nC	$V_{DS} = -10V, V_{GS} = -4.5V, I_D = -10A$
Total Gate Charge	Qg					$V_{DS} = -10V, V_{GS} = -10V, I_D = -10A$
Gate-Source Charge	Q <sub>gs</sub>	_	3.4	_		$V_{DS} = -10V, V_{GS} = -10V, I_D = -10A$
Gate-Drain Charge	Q <sub>gd</sub>		11.9	_		$V_{DS} = -10V, V_{GS} = -10V, I_D = -10A$
Turn-On Delay Time	t <sub>D(on)</sub>		7.5	15	ns	
Turn-On Rise Time	tr	_	9.9	20		$V_{DD} = -15V, I_D = -1A, V_{GS} = -10V,$
Turn-Off Delay Time	t <sub>D(off)</sub>	_	108.0	216		$R_{GEN} = 6\Omega$
Turn-Off Fall Time	t <sub>f</sub>	_	76.5	153	1	

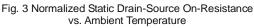
 Short duration pulse test used to minimize self-heating effect.
 Guaranteed by design. Not subject to product testing. Notes:











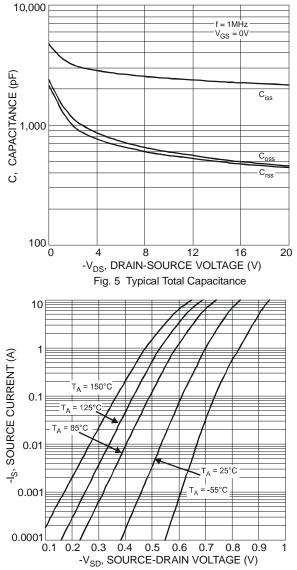
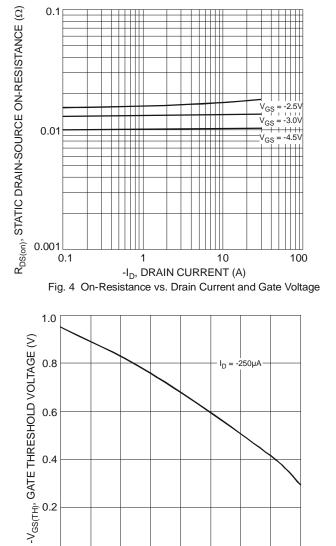


Fig. 7 Reverse Drain Current vs. Source-Drain Voltage



<sup>6</sup> 0 -50 -25 0 25 50 75 100 125 150 T<sub>A</sub>, AMBIENT TEMPERATURE (°C) Fig. 6 Gate Threshold Variation vs. Ambient Temperature

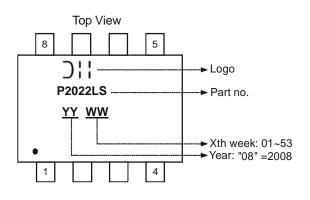


### Ordering Information (Note 7)

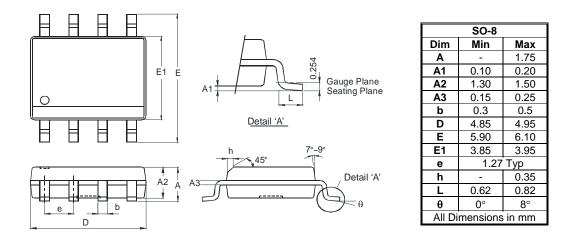
Part Number	Case	Packaging
DMP2022LSS-13	SO-8	2500/Tape & Reel
201120010		2000, 1000

Notes: 7. For packaging details, go to our website at http://www.diodes.com/datasheets/ap02007.pdf.

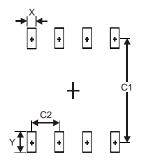
### **Marking Information**



# **Package Outline Dimensions**



# **Suggested Pad Layout**



Dimensions	Value (in mm)
Х	0.60
Y	1.55
C1	5.4
C2	1.27



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